## **DESCRIPTION**

The IS31LT3954\_IS32LT3954 is a DC-to-DC switching converter, which integrate an N-channel MOSFET to operate in a buck configuration. The device supply a wide input voltage between 4.5V and 38V and provides a constant current of up to 3A for driving a single LED or multiple series connected LEDs.

The external resistor,  $R_{\text{SET}}$ , is used to adjust LED output current, which allowing the output voltage to be automatically adjusted for a variety of LED configurations.

The IS31LT3954\_IS32LT3954 operates in a fixed frequency mode during switching. There is an external resistor connected between the VCC and TON pins used to configure the on-time (switching frequency). The switching frequency is dithered for spread spectrum feature to spread the electromagnetic emitting energy into a wider frequency band. It is helpful to optimize the EMI performance.

A logic input PWM signal to the enable (EN) pin is applied to adjust the LED current. The brightness of LED is proportional to the duty cycle of the PWM signal.

True average output current operation is achieved with fast transient response by using cycle-by-cycle, controlled on-time method.

IS31LT3954\_IS32LT3954 is available in an SOP-8-EP package with an exposed pad for enhanced thermal dissipation. It operates from 4.5V to 38V over the temperature range of -40°C to +125°C.

#### **FEATURES**

- Wide input voltage supply from 4.5V to 38V
  - Withstand 40V load dump
- ±5% true average output current control
- 3A maximum output over operating temperature range
- Cycle-by-cycle current limit
- Integrated high-side MOSFET switch
- Dimming via direct logic input or power supply voltage
- Internal control loop compensation
- Under-voltage lockout (UVLO) and thermal shutdown protection
- 2µA low power shutdown
- Spread spectrum to optimize EMI
- Robust fault protection and reporting function:
  - Pin-to-GND short
  - Component open/short faults
  - Adjacent pin-to-pin short
  - LED open/short
- AEC-Q100 qualification
  - IS32LT3954 only

## **QUICK START**



Figure 1: Photo of IS31LT3954\_ IS32LT3954 Evaluation Board

#### RECOMMENDED EQUIPMENT

- 38VDC power supply
- 1 pcs of LED panel (3W LEDs, 4LEDs in parallel and then 10 LEDs in series on each panel)
- Multi-meter

### **RECOMMENDED INPUT AND OUTPUT RATINGS**

- Input: 4.5~38VDC
- Output: 1~10 LEDs in series/3A

### **ABSOLUTE MAXIMUM RATINGS**

Input voltage ≤ 42VDC

Caution: Do not exceed the conditions listed above, otherwise the board will be damaged.

## **PROCEDURE**

The IS31LT3954\_IS32LT3954 DEMO Board is fully assembled and tested. Follow the steps listed below to verify board operation.

Caution: Do not turn on the power supply until all connections are completed.

- 1) Connect the positive terminal of the power supply to the VCC of the board and the negative terminal of the power supply to the GND of the board.
- Connect the negative of the one of the LED panel (LED arrays) to the LED- terminal. And connect the positive of the LED panel (LED arrays) to the LED+ terminal.
- 3) Select  $R_{SET}$  register on the DEMO Board by JP1~JP4 to set output current, that  $I_{OUT}$ =0.2/ $R_{SET}$ .
- 4) Select EN/PWM pin to VCC by JP6 or connect to a PWM signal generator. Note: when connect to the PWM signal, the JP6 must be open to avoid PWM generator damage.
- 5) Set FAULTB pin to VCC by JP5 or feedback to a MCU. Note: when feedback to the MCU, the JP5 must be open and pulled up on MCU site to avoid MCU damage.
- 6) Turn on the power supply and the LED panels (LED arrays) will be lighted up.

## **ORDER INFORMATION**

Part No.	Temperature Range	Package
IS31LT3954-GRLS4-EB IS32LT3954-GRLA3-EB	-40°C to +125°C (Industrial) -40°C to +125°C (Automotive)	SOP-8-EP, Lead-free

For pricing, delivery, and ordering information, please contacts Lumissil's analog marketing team at analog@Lumissil.com or (408) 969-6600.

#### **DETAILED DESCRIPTION**

## **OUTPUT CURRENT SETTING**

The LED current is configured by an external sense resistor,  $R_{\text{SET}}$ , with a value determined as follows Equation (1):

$$I_{LED} = V_{ER} / R_{SET} \tag{1}$$

Where  $V_{FB} = 0.2V$  (Typ.).

Note that  $R_{\text{SET}}$ = 0.0667 $\Omega$  is the minimum allowed value of sense resistor to maintain switch current below the specified maximum value.

Table 1 R<sub>SET</sub> Resistance Versus Output Current

R <sub>SET</sub> (Ω)	Nominal Average Output Current (mA)
0.2	1000
0.1	2000
0.0667	3000

The  $R_{\text{SET}}$  should be a 1% resistor with enough power tolerance and good temperature characteristic to ensure accurate and stable output current.

### FREQUENCY SELECTION

During switching the IS32LT3954 operates in a consistent on-time mode. The on-time is adjusted by an external resistor,  $R_{\text{TON}}$ , which is connected between the VCC and TON pins.

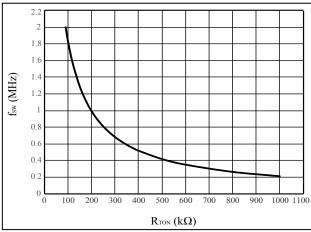


Figure 2: Operating Frequency vs. R<sub>TON</sub> Resistance

The approximate operating frequency can be calculated by below Equation (2) and (3):

$$t_{oN} = \frac{k \times (R_{TON} + R_{INT}) \times V_{OUT}}{V_{CC}}$$
 (2)

$$f_{SW} = \frac{1}{k \times (R_{TON} + R_{INT})}$$
 (3)

Where k= 0.00458, with  $f_{SW}$  in MHz,  $t_{ON}$  in  $\mu s$ , and  $R_{TON}$  and  $R_{INT}$  (internal resistance,  $20k\Omega$ ) in  $k\Omega$ .

Higher frequency gets smaller components size but increases the switching losses and high-side MOSFET gate driving current, and may not allow sufficiently high or low duty cycle. Lower frequency gives better performance at larger components size.

#### **INDUCTOR**

Inductor value involves trade-offs in performance. Larger inductance reduces inductor current ripple that obtains smaller output current ripple, however it also brings in unwanted parasitic resistance that degrade the performance. Smaller inductance has compact size and lower cost, but introduces higher ripple in the LED string. Use the following equations to estimate the approximate inductor value:

$$L = \frac{(V_{CC} - V_{LED}) \times V_{LED}}{f_{SW} \times \Delta I_L \times V_{CC}}$$
(4)

Where  $V_{CC}$  uses the minimum input voltage in volts,  $V_{LED}$  is the total forward voltage of LED string in volts,  $f_{SW}$  is the operation frequency in hertz.  $\Delta I_L$  is the current ripple in the inductor. Select an inductor with a rating current over output average current and the saturation current over the Over Current Protection (OCP) current threshold  $I_{SWLIM}$ .

Since IS32LT3954 is a Continuous Conduction Mode (CCM) buck driver which means the valley of the inductor current,  $I_{\text{MIN}},$  should not drop to zero all the time, the  $\Delta I_{\text{L}}$  must be smaller than 200% of the average output current.

$$I_{MIN} = I_{LED} - \frac{\Delta I_{L}}{2} > 0 \tag{5}$$

Besides, the peak current of the inductor,  $I_{MAX}$ , must be smaller than  $I_{SWLIM}$  to prevent device from triggering OCP, especially the output current is set to high level.

$$I_{\text{\tiny MAX}} = I_{\text{\tiny LED}} + \frac{\Delta I_{\text{\tiny L}}}{2} < I_{\text{\tiny SWLIM}} \tag{6}$$

On the other hand, the  $\Delta I_L$  has to be higher than 10% of the average output current all the time to ensure the system stability. For the better performance, recommend to choose the inductor current ripple  $\Delta I_L$  between 10% and 50% of the average output current.

$$0.1 \times I_{LED} \le \Delta I_{L} \le 0.5 \times I_{LED} \tag{7}$$

Below figure shows the inductance selection based on operating frequency and LED current at 30% inductor current ripple. If the lower operating frequency is adopted, either the larger inductance or current ripple should be used.

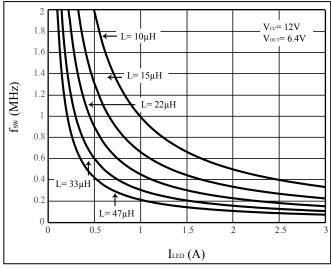


Figure 3: Inductance Selection Based On 30% Current Ripple

Note: The Wurth Elektronik WE-PD 744770xxx and 744771xxx series are the suitable inductance value choice.

## **FAULT HANDLING**

The IS32LT3954 is designed to detect the following faults and report via FAULTB pin:

- Pin open
- Pin-to-ground short
- Pin-to-neighboring pin short
- Output LED string open and short
- External component open or short

Please check Table 2 for the detail of the fault actions.

## **PCB LAYOUT CONSIDERATION**

As for all switching power supplies, especially those providing high current and using high switching frequencies, layout is an important design step. If layout is not carefully done, the operation could show instability as well as EMI problems.

The high dV/dt surface and dI/dt loops are big noise emission source. To optimize the EMI performance, keep the area size of all high switching frequency points with high voltage compact. Meantime, keep all traces carrying high current as short as possible to minimize the loops.

- (1) Wide traces should be used for connection of the high current paths that helps to achieve better efficiency and EMI performance. Such as the traces of power supply, inductor  $L_1$ , current recirculating diode  $D_1$ , LED load and ground.
- (2) Keep the traces of the switching points shorter. The inductor  $L_1$ , LX and current recirculating diode  $D_1$  should be placed as close to each other as possible and the traces of connection between them should be as short and wide as possible.
- (3) To avoid the ground jitter, the components of parameter setting,  $R_{\text{SET}}$ , should be placed close to the device and keep the traces length to the device pins as short as possible. On the other side, to prevent the noise coupling, the traces of  $R_{\text{SET}}$  should either be far away or be isolated from high-current paths and high-speed switching nodes. These practices are essential for better accuracy and stability.
- (4) The capacitor  $C_{\text{IN}}$  should be placed as close as possible to VCC pin for good filtering.
- (5) Place the bootstrap capacitor  $C_{\text{BOOT}}$  close to BOOT pin and LX pin to ensure the traces as short as possible.
- (6) The connection to the LED string should be kept short to minimize radiated emission. In practice, if the LED string is far away from the driver board, an output capacitor is recommended to be used and placed on driver board to reduce the current ripple in the connecting wire.
- (7) The thermal pad on the back of device package must be soldered to a sufficient size of copper ground plane with sufficient vias to conduct the heat to opposite side PCB for adequate cooling.





Table 2 Fault Actions

Table 2 Fault Actions							
Fault Type	LED String		Detect Condition FAULTB Pin		Fault Recovering		
Inductor shorted	Dim	Trigger OCP. Turn off high-side MOSFET immediately. Retry after 1ms.		Pull Low after second OCP cycle.		Inductor shorted removed. No OCP triggered and FAULTB pin recover after 10ms.	
R <sub>SET</sub> short	Dim	Trigger OCP. Turn off high-side MOSFET immediately. Retry after 1ms.		Pull Low after second OCP cycle.		R <sub>SET</sub> shorted removed. No OCP triggered and FAULTB pin recover after 10ms.	
R <sub>SET</sub> open	Off		voltage exceeds 2V. Turn off IOSFET immediately. Retry after	Pull Low immediately.		R <sub>SET</sub> open removed. The FB pin voltage drops below 1.55V and FAULTB pin recover after 10ms.	
		No PWM dimming:	FB pin average voltage drops below 0.2V for 10ms.	No PWM dimming:	Pull Low after 10ms.	LED open removed. FB average	
LED string open	Off	PWM dimming:	FB pin average voltage drops below 0.2V after 25us deglitch time and keeps for 128 PWM cycles.	PWM dimming:	Pull low after 128 PWM cycles.	voltage keep at 0.2V for 10ms and FAULTB pin recover.	
LED string shorted Off		No PWM dimming:	Filter V <sub>LX</sub> to get V <sub>OUT</sub> , if V <sub>OUT</sub> <1V for 10ms	No PWM dimming:	Pull Low after 10ms.	Shorted removed. V <sub>OUT</sub> >1V for 10m	
	Off	PWM dimming:	Filter V <sub>LX</sub> to get V <sub>OUT</sub> , if V <sub>OUT</sub> <1V after 25us deglitch time and keeps for 128 PWM cycles.	PWM dimming:	Pull low after 128 PWM cycles.	and FAULTB pin recover.	
LED string shorted to GND	Off		P. Turn off high-side MOSFET y. Retry after 1ms.	Pull Low after second OCP cycle.		Shorted removed. No OCP triggered and FAULTB pin recover after 10ms.	
BOOT capacitor open	Dim	V <sub>CC</sub> -V <sub>SW</sub> >1.8V at high-side MOSFET ON (High-side can't fully turn on). Turn off high-side MOSFET immediately. Retry after 1ms.		Pull Low immediately		BOOT capacitor open removed, V <sub>CC</sub> -V <sub>SW</sub> <1.8V for 10ms and FAULTB pin recover.	
BOOT capacitor shorted		Bootstrap circuit UVLO and turn off high-side		No PWM dimming:	Pull Low after 10ms.	BOOT capacitor shorted removed.	
			mmediately.	PWM dimming:	Pull low after 128 PWM cycles.	Release from UVLO and FAULTB   recover after 10ms	
R <sub>TON</sub> resistor open	Dim		ceeds 20µs or trigger OCP, then n-side MOSFET immediately. 1ms.	Pull Low after 20µs or second OCP cycle.		R <sub>TON</sub> resistor open removed. No over 20us on-time or OCP triggered. FAULTB pin recover after 10ms	
R <sub>TON</sub> resistor shorted	Dim		operating at minimum on/off time, ger the other fault conditions.	No reporting		R <sub>TON</sub> resistor shorted removed.	
EN short to R <sub>SET</sub>	Off	EN/PWM w	vill be pulled low by R <sub>SET</sub> resistor.	No reporting		EN short to R <sub>SET</sub> removed.	

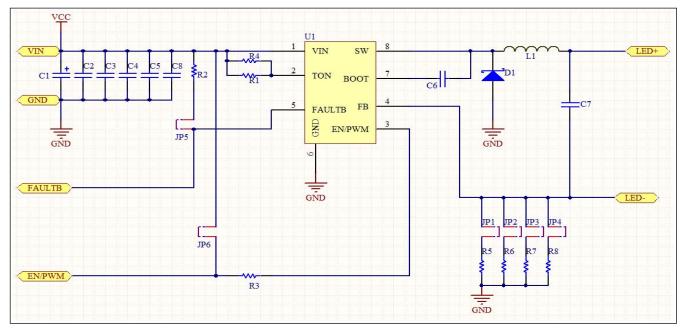


Figure 4: IS31LT3954\_IS32LT3954 Demo Board Schematic

# **BILL OF MATERIALS**

Name	Symbol	Description	Qty	Supplier	Part No.
IC	U1	Constant current LED driver	1	Lumissil	IS31LT3954-GRLS4-TR/ IS32LT3954-GRLA3-TR
E-Cap	C1	CAP,47µF,63V,±20%	1	Panasonic	EEV-TG1J470P
Capacitor	C2,C3,C7	NC			
Capacitor	C4,C5,C8	CAP,10µF,50V,±10%,SMD	3	Yageo	AC1206KKX7R9BB106
Capacitor	C6	CAP,100nF,50V,±10%,SMD	1	Yageo	AC0805KKX7R9BB104
Resistor	R1	RES,430k,1/8W,±5%,SMD	1	Yageo	AC0805JR-07430KL
Resistor	R2	RES,10k,1/8W,±5%,SMD	1	Yageo	AC0805JR-0710KL
Resistor	R3	RES,1k,1/8W,±5%,SMD	1	Yageo	AC0805JR-0701KL
Resistor	R5~R8	RES,0.27R,1/4W,±1%,SMD	4	Yageo	RL1206FR-070R27L
Resistor	R4	NC			
Diode	D1	5A,100V, Power DI 5	1	Diodes	PDS5100
Inductor	L1	10μH±20%,Isat≥10.5A,SMD	1	Würth Elektronik	7447709100

Note: Bill of materials refers to Figure 4 above.



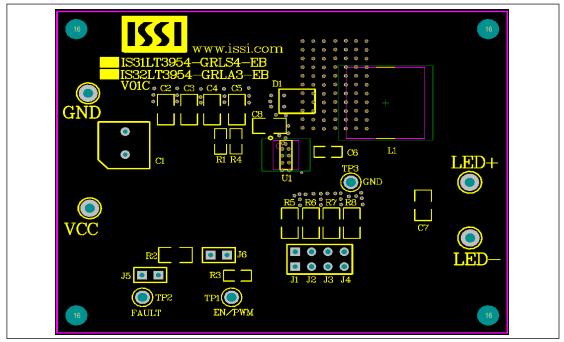


Figure 5: Board Component Placement Guide - Top Layer

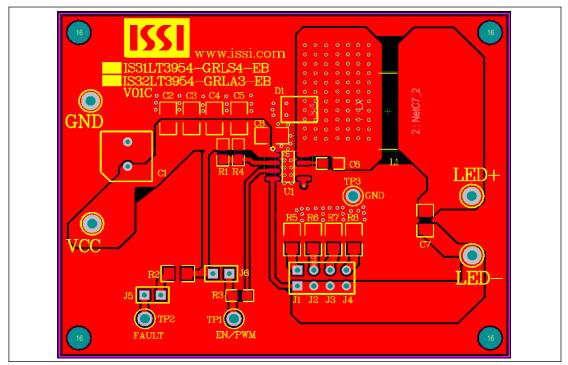


Figure 6: Board PCB Layout - Top Layer

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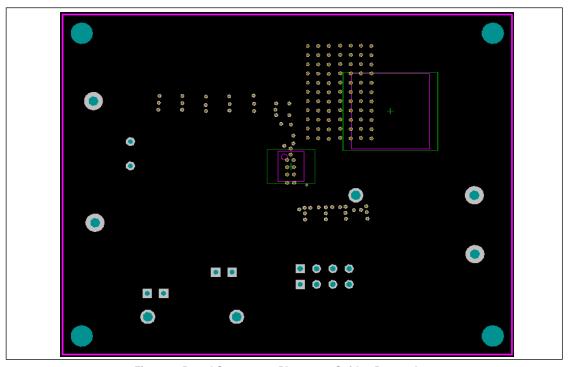


Figure 7: Board Component Placement Guide - Bottom Layer

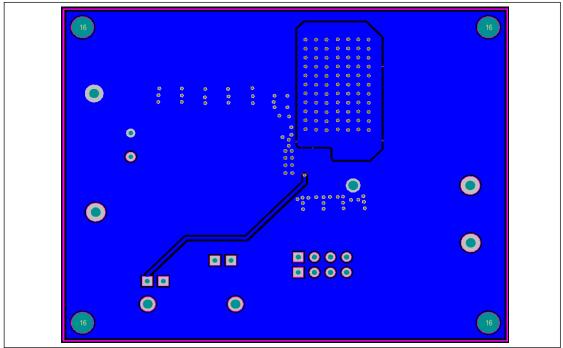


Figure 8: Board PCB Layout - Bottom Layer

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**REVISION HISTORY** 

Revision	Detail Information	Date
А	Initial release	2018.06.26
В	Update BOM list	2020.09.15